



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : C08K 13/04 // (C08K 13/04, 3:08, 7:02)		A1	(11) International Publication Number: WO 98/00462
			(43) International Publication Date: 8 January 1998 (08.01.98)
(21) International Application Number: PCT/US97/11573 (22) International Filing Date: 27 June 1997 (27.06.97) (30) Priority Data: 60/020,914 28 June 1996 (28.06.96) US (60) Parent Application or Grant (63) Related by Continuation US 60/020,914 (CON) Filed on 28 June 1996 (28.06.96) (71) Applicant (for all designated States except US): TEXAS RESEARCH INSTITUTE AUSTIN, INC. [US/US]; 9063 Bee Caves Road, Austin, TX 78733-6201 (US). (72) Inventors; and (75) Inventors/Applicants (for US only): BRAY, Alan, V. [US/US]; 113 So. Cuernavaca, Austin, TX 78733 (US). MUSKOPF, Brian, A. [US/US]; 2005 Big Horn Drive, Austin, TX 78734 (US). DINGUS, Michael, L. [US/US]; 1515 Oxford, Austin, TX 78704 (US). (74) Agent: NATION, Floyd, R.; Arnold, White & Durkee, P.O. Box 4433, Houston, TX 77210 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, ARIPO patent (GH, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.	
(54) Title: HIGH DENSITY COMPOSITE MATERIAL			
(57) Abstract			
The present invention is related to a family of materials that may act as a replacement for lead in applications where the high density of lead is important, but where the toxicity of lead is undesirable. The present invention more particularly provides a high density material comprising tungsten, fiber and binder. Methods and compositions of such materials and applications thereof are disclosed herein.			